

AN 1983:130963 CAPLUS
DN 98:130963
TI Sintered composite as thermal expansion buffer
PA Hitachi Cable, Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 4 pp.
CODEN: JKXXAF

DT Patent
LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	JP 57152438	A	19820920	JP 1981-37538	19810316
PRAI	JP 1981-37538		19810316		

AB For use as a thermal expansion buffer in soldering a Si wafer and Cu lead wires, powdered Fe-Ni alloys containing 36-42% Ni are coated with Mo or W 0.2 μ thick, mixed with 20-80% powdered Cu having an elec. conductivity $\geq 100\%$, compacted, sintered at 700° for 30 min, and rolled repeatedly with intermediate annealing 10 min at 700°. The thermal expansion coefficient and elec. conductivity increases linearly with increasing Cu content. Without the coating, the values remain unchanged.